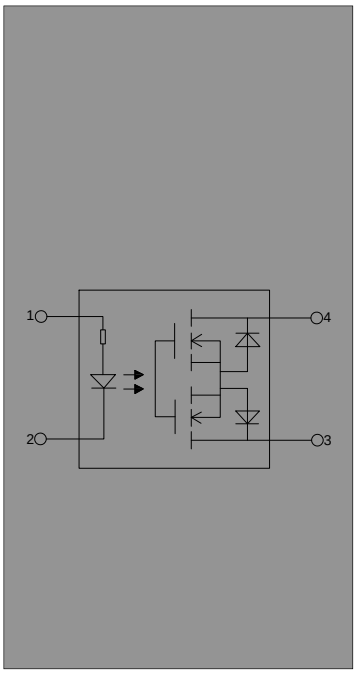
DESCRIPTION:

The products are 4-pin optical relays. The device is a very small outline non-leaded photorelay suitable for surface-mount assembly. It consists of an infrared LED optically coupled to a photo-MOSFET and is housed in a SSON4 package. It features low output capacitance, COFF, and thus fast on/off switching of a high-frequency signal, making it ideal for switching applications in high-speed testers. The products are widely used in automatic test equipment, high-speed logic IC testers, high-speed memory testers and measuring instruments.



MAIN FEATURES

Isolation voltage 500 Vrms
Operating temperature range -40°C to 125°C
REACH & RoHS compliance
HBM: H3A; MM: M4; CDM: C3

ABSOLUTE MAXIMUM RATINGS (Temperature=25°C)

Input	Input Forward Voltage	V_{IN}	6	V
	Reverse Voltage	V_R	6	V
	Input Power Dissipation	P_D	75	mW
Detector	Off-state Output Terminal Voltage	V_{OFF}	60	V
	On-state Current	I_{ON}	1	A
	On-state Current (pulsed)	I_{ONP}	3	A
Isolation Voltage		V_{iso}	500	Vrms
Operating Temperature		T_{opr}	-40~125	
Junction Temperature		T_j	135	
Storage Temperature		T_{stg}	-55~135	
Soldering Temperature		T_{sol}	260	

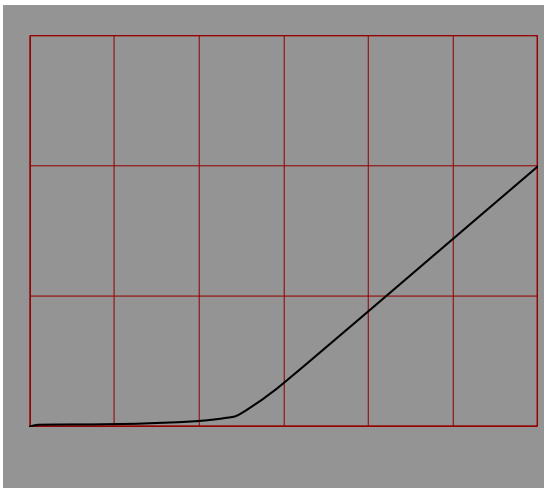
NOTE1:

Characteristics Curves

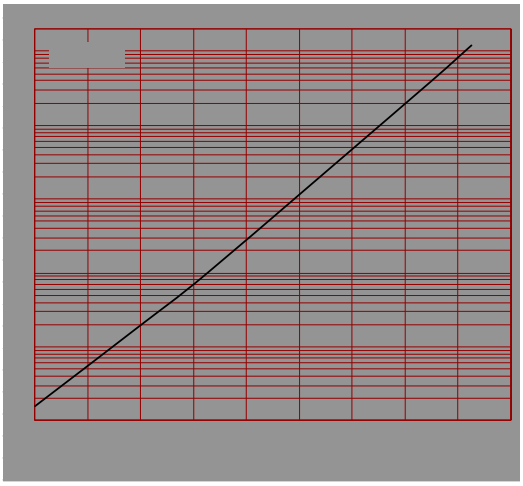
Operating Voltage vs. Ambient Temperature

On-state Current vs. Ambient Temperature

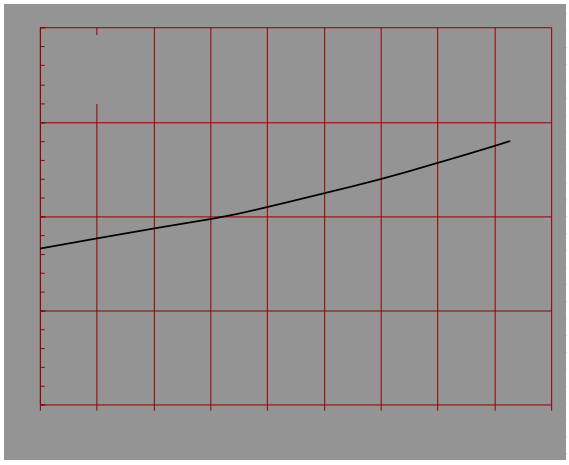
Off-state Current vs. Off-state Voltage

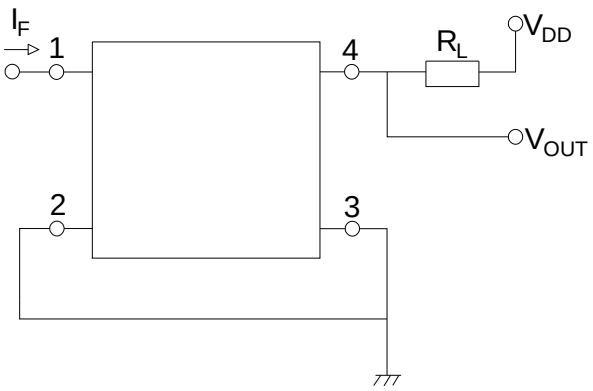


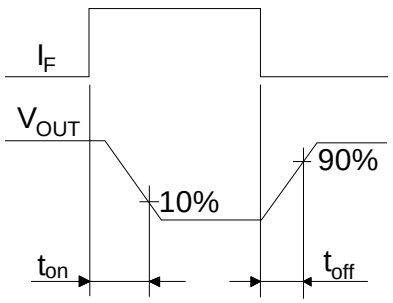
Off-state Current vs. Ambient Temperature



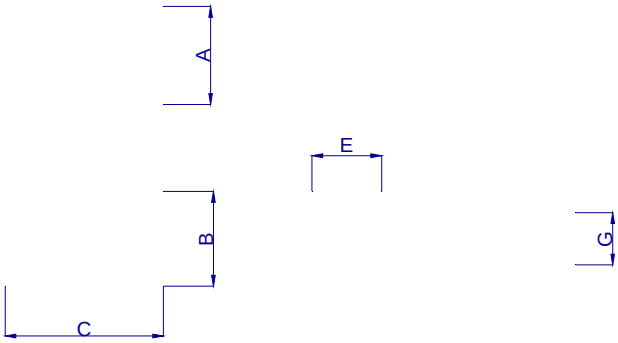
On Resistance vs. Ambient Temperature







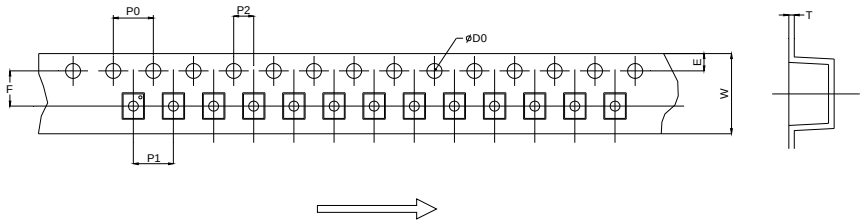
Package Dimension (Unit: mm)



Ref.	Dimensions					
	Millimeters			Inches		
	Min.	Typ.	Max.	Min.	Typ.	Max.
A	1.30		1.70	0.051		0.067
B	1.65		2.05	0.065		0.081
C						
D	0.10		0.50	0.004		0.020
E	0.88		1.28	0.035		0.050
F						
G	0.60			0.024		
H						

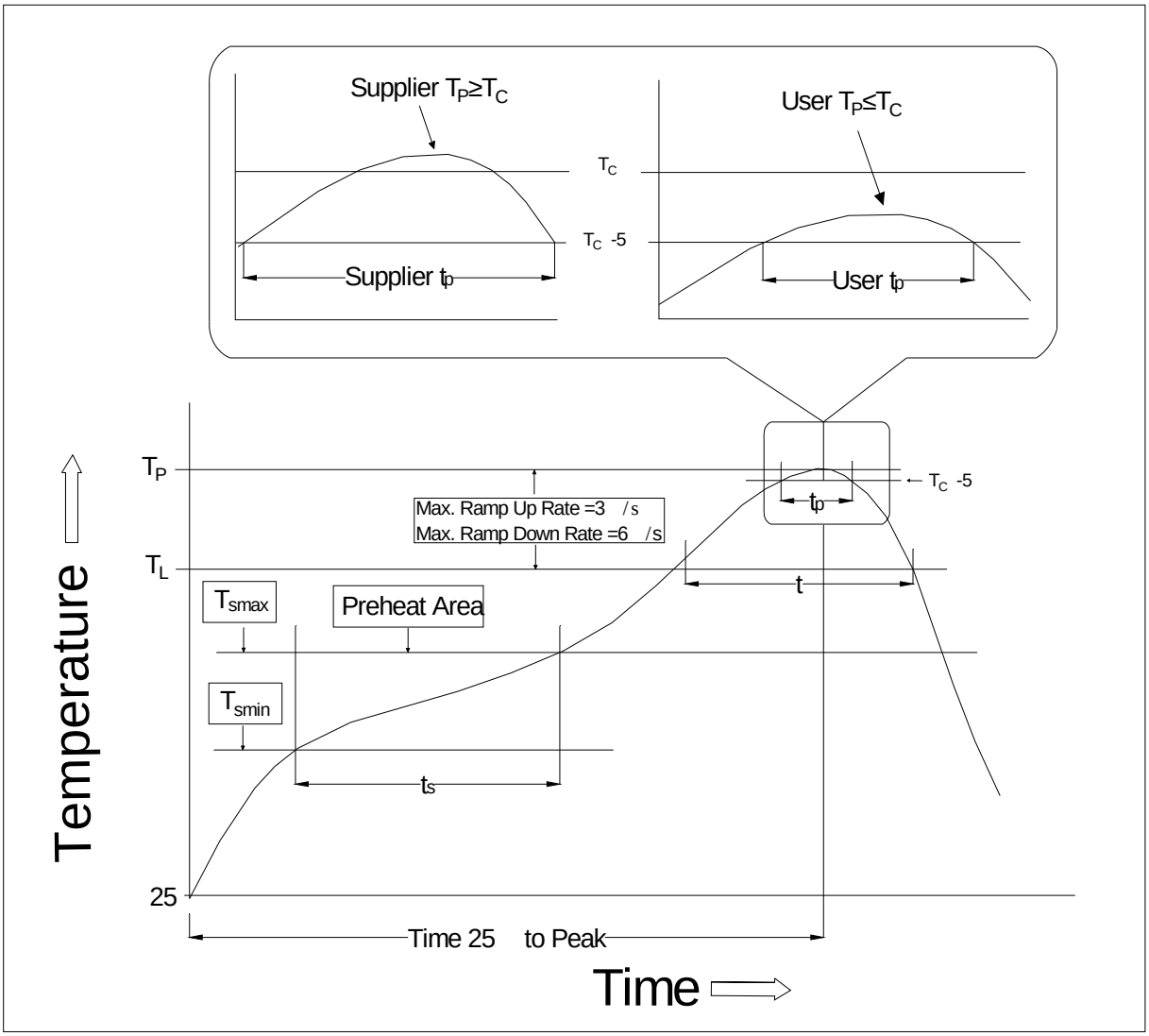


CARRIER TAPE SPECIFICATIONS (Dimensions in mm unless otherwise stated)



Ref.	Dimensions					
	Millimeters			Inches		
	Min.	Typ.	Max.	Min.	Typ.	Max.
D0		1.50	1.60		0.059	0.063
P0	3.90	4.00	4.10	0.154	0.157	0.161
P1	3.90	4.00	4.10	0.154	0.157	0.161
P2	1.90	2.00	2.10	0.075	0.079	0.083
E	1.65	1.75	1.85	0.065	0.069	0.073
F	3.40	3.50	3.60	0.134	0.138	0.142
T	0.20	0.25	0.30	0.008	0.010	0.012
W	7.70	8.00	8.30	0.303	0.315	0.327

REFLOW INFORMATION



Temperature Min. (Tsmin)	100	150
Temperature Max. (Tsmax)	150	200
Time (ts) from (Tsmin to Tsmax)	60-120 seconds	60-120 seconds
Ramp-up Rate (tL to tP)	3 /second max.	3 /second max.
Liquidus Temperature (TL)	183	217
Time (tL) Maintained Above (TL)	60-150 seconds	60-150 seconds
Peak Body Package Temperature	235 +0 /-5	260 +0 /-5
Time (tP) within 5 of 260	10 seconds	10 seconds
Ramp-down Rate (TP to TL)	3-6 /second	3-6 /second
Time 25 to Peak Temperature	6 minutes max.	8 minutes max.

Note:

1. Reflow soldering is recommended at the temperatures and times shown, no more than three times.

2. Avoid direct contact between the epoxy body twe bc Co., Z Z „E 0 P ð ° @ T